distribution thereof, such that the viscosity of the sealing material, which contains an inorganic filler, does not increase even at high inorganic filler loading (Patent Documents 5 and 6). However, these sealing materials do not have sufficiently reduced viscosity and enhanced molding property, and thus, prior to the present invention, no semiconductor sealing material having a reduced viscosity upon sealing with high inorganic filler loading, and enhanced molding property was available.

[Patent Document 1] Japanese Unexamined Patent Application, First Publication No. 2007-231159

[Patent Document 2] Japanese Unexamined Patent Application, First Publication No. 2007-262385

[Patent Document 3] Japanese Unexamined Patent Application, First Publication No. 2006-225630

[Patent Document 4] Japanese Unexamined Patent Application, First Publication No. 2002-284859

[Patent Document 5] Japanese Unexamined Patent Application, First Publication No. 2005-239892

[Patent Document 6] WO2007/132771

SUMMARY OF THE INVENTION

It is an object of the present ~~invention~~disclosure to provide a resin composition, and particularly a semiconductor sealing material having a reduced viscosity upon sealing and a further enhanced molding property even with high loading of an inorganic filler, and to provide an amorphous siliceous powder

that is suitable for preparation thereof.

In a first aspect of the present ~~invention~~disclosure, provided is an amorphous siliceous powder comprising Si and Al in a combined content thereof in the powder is 99.5% by mass or more in terms of their oxides; a content of Al in a first portion of the powder, having a particle size range of 15 μm or more to less than 70 μm, is 100 to 30000 ppm in terms of its oxide; a content of Al in a second portion of the powder, having a particle size range of 3 μm or more to less than 15 μm, is 100 to 7000 ppm in terms of its oxide; and a content of Al in the powder including the entire particle size range is 100 to 25000 ppm in terms of its oxide, wherein~~. In the present invention, it is preferable that~~ a ratio (A/B) of (A) the content of Al in the first portion of the powder to (B) the content of Al in the second portion of the powder, is 1.0 to 20. It is also preferable that the powder has a multimodal particle size distribution with at least two peaks in a frequency particle size distribution, in which a maximum frequency value of a first peak is located between a particle size range of 15 to 70 μm, a maximum frequency value of a second peak is located between a particle size range of 3 to 10 μm and an average particle diameter is 5 to 50 μm.

In a second aspect of the present ~~invention~~disclosure, provided is a method for producing the amorphous siliceous powder of the first aspect of the present ~~invention~~disclosure, the method including spraying from separate burners a first raw material siliceous powder having an average particle diameter of 15 to 70 μm and a

content of Al of a first Al source material of 100 to 30000 ppm in terms of its oxide, and a second raw material siliceous powder having an average particle diameter of 3 to 10 μm and a content of Al of a second Al source material of 100 to 7000 ppm in terms of its oxide, into a high temperature flame formed from a flammable gas and a supporting gas.

In third aspect of the present ~~invention~~disclosure, provided is a resin composition containing the amorphous siliceous powder of the first aspect of the present ~~invention~~disclosure, and a resin. The resin used for the composition preferably comprises an epoxy resin. In a fourth aspect of the present ~~invention~~disclosure, provided is a semiconductor sealing material including the composition.

According to the present ~~invention~~disclosure, it is possible to provide a resin composition, in particular a semiconductor sealing material, which is excellent in fluidity, viscosity property and molding property. It is also possible to provide an amorphous siliceous powder suitable for preparing the composition.

DETAILED DESCRIPTION OF THE INVENTION

In the amorphous siliceous powder of the present invention, the content of Al in a first portion of the powder, having a particle size range of 15 μm or more to less than 70 μm, is 100 to 30000 ppm in terms of its oxide, the content of Al in a second portion of the powder, having a particle size range of 3 μm or more to less than 15 μm, is 100 to 7000 ppm in terms of its oxide, and the content of Al in the powder